# Test beam results of 3D pixel sensors for the Phase-2 CMS Tracker with the RD53A and CROC readout chips

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on behalf of the CMS Inner Tracker sensors group

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- Introduction to the High-Luminosity Upgrade for the CMS Inner Tracker
- Layout of 3D pixel sensors
- Read-out chips: CROC and RD53A
- Irradiation and test beam
- Test beam results
- Conclusions

# The CMS Inner Tracker upgrade for the High-Luminosity LHC



- Instantaneous luminosity peaks at 7.5x10<sup>34</sup> cm<sup>2</sup>/s
- 200 collisions per bunch crossing
- CMS needs an upgrade to cope with such conditions. The silicon tracker will be completely replaced to sustain the foreseen radiation levels, especially in the innermost layer of the Inner Tracker (IT)



- Active thickness: 285µm  $\rightarrow$  150µm to reduce power dissipation
- Pixel pitch:  $100x150\mu m^2 \rightarrow 25x100\mu m^2$  to reduce pixel occupancy
- Two sensor technologies: planar pixels + 3D pixels in the innermost layer
  - 3D pixel sensors are more radiation tolerant
  - Simulations for TBPX L1 show thermal runaway issues in planar sensors

## High-Luminosity upgrade of the CMS IT layout

- Tracking coverage extended up to  $|\eta| = 4.0$
- Tracker Barrel Pixel (TBPX): 4 layers

Have a look at Massimiliano Antonello's

- Tracker Forward Pixel (TFPX): 8 small disks per side
- Tracker Endcap Pixel (TEPX): 4 large disks per side
- Hybrid modules with 1x2 and 2x2 readout chips





Grad

1.03

with replacement after

~6 years of operation Runs 4+5

1E16 1MeV nea

1.88





- Low resistivity silicon layer bonded to high resistivity substrate using the Direct Wafer Bonding (DWB) technique: Si-on-Si
  - The total thickness after thinning is 250µm with **150µm of active thickness**.
- Columnar implants penetrate the substrate from the same face: single-side Deep Reactive Ion Etching (DRIE) process
  - p<sup>+</sup> columns in contact with the backside of the sensor
  - **n**<sup>+</sup> columns connected through the bump bonding pads to the readout chip  $\rightarrow$  ~115µm in FBK and ~130µm in CNM
  - They have a  $5\mu m$  diameter in FBK and  $8\mu m$  diameter in CNM. They are filled with polysilicon.
- The bias voltage is applied to the ohmic contact from the sensor backside.

- The read-out chip (ROC) is connected to the sensor with the bump-bonding technique.
- The read-out chip design has been carried out by the RD53 Collaboration
  - · 65nm CMOS technology
  - $\cdot~~50x50\mu m^2$  pixel matrix  $\rightarrow~$  diagonal sensor-chip mapping
  - · Digital readout with Time-Over-Threshold
  - · Serial powering via on-chip shunt-LDO regulators  $\rightarrow$  Have a look at Antonio Cassese's presentation!
  - **RD53A** was the first prototype common for ATLAS and CMS  $\rightarrow$  R&D purposes (until beginning of 2022)
    - Three analog front-ends: synchronous, linear and differential
    - $\cdot$  76800 pixel channels  $\rightarrow$  26112 in the linear front-end
    - · 192 rows x 400 columns → **192 rows x 136 columns**
  - > CMS' choice was to have a ROC with **only linear front-end**: **CROC** 
    - Currently available for sensor R&D purposes
    - Final version foreseen for the second half of 2023
    - 145152 pixel channels  $\rightarrow$  336 rows x 432 columns
- In order to operate the modules, a calibration is needed: Tuning to a threshold of 1000e- is feasible before and after irradiation, although with a higher noise in the latter.











## Data taking @ DESY and CERN SPS test beam areas:

- DESY: 5.2 GeV electron/positron beam
- CERN: 120 GeV pion beam
- Setup: EUDET-type telescope
  - Two arms: downstream and upstream
  - $^{\circ}$  5-6 Mimosa26 planes with square pixels of 18.4  $\mu m$  pitch
  - · Mimosa26 resolution around 2 µm on each coordinate
  - · Telescope resolution depending on the DUT position
  - 576 rows x 1152 columns
- The **D**evices **U**nder **T**est (**DUTs**) are placed inside a cooling box in the middle of the telescope.
- Irradiation of 3D pixel modules @ several facilities:
  - CERN PS: 24 GeV protons
  - Karlsruhe Institute of Technology (KIT): 25 MeV protons
  - Fermilab Irradiation Test Area (ITA): 400 MeV protons
  - Institut Pluridisciplinaire Hubert Curien (IPHC): 23 MeV protons



 The results shown in this presentation correspond to modules irradiated in these two facilities

> CERN PS: TID  $\simeq$  0.5 GRad per 1x10<sup>16</sup>n<sub>eq</sub>/cm<sup>2</sup> KIT: TID  $\simeq$  1.5 GRad per 1x10<sup>16</sup>n<sub>eq</sub>/cm<sup>2</sup>

### Efficiency as a function of bias voltage at normal incidence: higher than 97% after full depletion (already at 5V)

- The columns are passive material and give rise to inefficiencies  $\rightarrow$  it can be recovered by tilting the modules
- Less than 1% of masked (stuck+noisy) channels  $\rightarrow$  noisy = occupancy higher than 2x10<sup>-5</sup>
- The modules were tuned to average thresholds of 1000-1200e-•



**TREDI 2023** 

# Results (I): CROC 3D modules irradiated at 1x10<sup>16</sup>n<sub>eq</sub>/cm<sup>2</sup>





**TREDI 2023** 

cell

pixel

the

<u>\_</u>

Efficiency map

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# Results (II): CROC 3D modules irradiated at 1x10<sup>16</sup>n<sub>eq</sub>/cm<sup>2</sup>





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## Results: RD53A 3D modules irradiated at 1.5-1.8x10<sup>16</sup>n<sub>e0</sub>/cm<sup>2</sup>





**TREDI 2023** 



- RD53A FBK Stepper-2 irradiated at 1.4x10<sup>16</sup>n<sub>ce</sub>/cm<sup>2</sup> -



- RD53A FBK Stepper-1 irradiated at 1.5x10<sup>16</sup>n /cm<sup>2</sup> -



Noisy pixels defined with a cut at  $2\times10^{-5}$  occupancy (1% of the L1 occupancy)

- The increase in the number of noisy channels correlates with fluence and bias voltage
- More noise observed in Stepper-1 (130µm n<sup>+</sup> column) than in Stepper-2 (115µm n<sup>+</sup> column)
  - · Stepper-1 irradiated at  $1.5 \times 10^{16} n_{eq}/cm^2$ : ~14% at V<sub>bias</sub> = 140V
  - Stepper-2 irradiated at  $1.4 \times 10^{16} n_{eq}^{2}$  cm<sup>2</sup>: ~1% at V<sub>bias</sub> = 140V
  - · Stepper-2 irradiated at  $1.8 \times 10^{16} n_{eq}^{-1}$ /cm<sup>2</sup>: below 1% up to V<sub>bias</sub> = 160V
- The CROC CNM (130 $\mu m$  n^+ column) irradiated at 1x10^{16}n\_{eq}/cm^2 seems to behave similar to Stepper-1
- The cause is still under investigation:
  - 3D geometry producing electric field peaks that generate avalanche? Relation to the n<sup>+</sup> column length?



- RD53A FBK Stepper-2 irradiated at 1.8x10<sup>16</sup>n<sub>ed</sub>/cm<sup>2</sup> -



Fiducial acceptance: excluding the noisy pixels corresponding to a damaged region where the pixels were already noisy at very low bias voltages

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- 3D pixel sensors have been chosen by CMS as the baseline technology for the innermost layer of the TBPX.
- CROC 3D modules have been irradiated to  $1 \times 10^{16} n_{eq}^{2}$  for the first time and show excellent performance.
- RD53A 3D modules iradiated to  $1.5 \times 10^{16} n_{eq}^{2}$  and  $1.8 \times 10^{16} n_{eq}^{2}$  fullfil the CMS requirements.
  - → 97% efficiency at normal incidence and 99% when the modules are tilted
  - → Comfortable margin of operation without the risk of thermal runaway
  - → Noisy channels below 2%
- The noisy behaviour present at high bias voltages and high fluences is still under investigation.
- Irradiation of CROC 3D modules to higher fluences is foreseen for 2023.

## BACKUP



## • First CROC modules have been irradiated at the CERN IRRAD facility

- → Tilted by 30° to achieve a uniform irradiation along columns
- Horizontal scan to achieve a uniform irradiation along rows
- In the backside of some modules there was an Al-foil that is used to estimate the fluence from spectroscopy:
  - · Cut into small pieces
  - Measure activity of each small piece

Fluence estimation in different regions (rows and columns)

- The spectroscopy results are consistent among the Al-foils of different modules with a 7% error on fluence.
  - → Not perfectly centered along Y (vertical direction)
  - Uniform irradiation along X (scanning direction)
  - → Focus on the region of interest:  $\sim 1 \times 10^{16} n_{eq} / cm^2$  TID  $\simeq 0.5 GRad$



#### Last irradiation campaigns of RD53A and CROC at IRRAD (CERN)











# RD53A FBK 3D modules irradiated at 2.0-2.5x10<sup>16</sup>n<sub>eg</sub>/cm<sup>2</sup> (I)



- The irradiation campaign that was carried out in May/June at CERN-PS with a 24GeV proton beam gave rise to **modules non-uniformly irradiated**.
- The aluminium foils placed behind the modules were used to estimate the fluence in different regions.





### Need of analyzing the data per regions of fluence !!



- Cut the Al-foil placed on the sensor surface during the irradiation in 8 small pieces.
- Measure activity of each small piece.
- Fit with bivariate Normal distribution to get an approximate irradiation profile.
- Define a **region of interest (ROI)** irradiated as uniform as possible:

### W5-R22: (2.6±0.09)x10<sup>16</sup>n<sub>ed</sub>/cm<sup>2</sup>

W11-R18: (2.1±0.08)x10<sup>16</sup>n<sub>e0</sub>/cm<sup>2</sup>



## RD53A FBK 3D modules irradiated at 2.0-2.5x10<sup>16</sup>n<sub>eq</sub>/cm<sup>2</sup> (II)



- The ROI irradiated at ~2.1x10<sup>16</sup> $n_{eq}$ /cm<sup>2</sup> reaches ~92% efficiency at 160V with ~7% of masked pixels.
- The ROI irradiated at ~2.6x10<sup>16</sup>n<sub>ed</sub>/cm<sup>2</sup> reaches ~90% efficiency at 180V with ~1% of masked pixels.

**Preliminary results!** 

